



EV Group and Teramount announce collaboration to implement innovative packaging technologies for photonic integrated circuits – March 9, 2022



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2020-2022 expected to be the first 3-year period of double-digit capex growth since 1993-1995. **More>>**

Global semiconductor sales increase 26.8% year-to-year in January

The Semiconductor Industry Association announced global semiconductor industry sales were

\$50.7 billion in the month of January 2022, an increase of 26.8% over the January 2021 total of \$40.0 billion and 0.2% less than the December 2021 total of \$50.9 billion. [More>>](#)



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EV Group and Teramount announce collaboration to implement innovative packaging technologies for photonic integrated circuits

The collaboration will leverage EVG's nanoimprint lithography (NIL) technology, expertise and services with Teramount's PhotonicPlug technology. [More>>](#)

Micron delivers world's most advanced 176-layer NAND data center SSD

Micron Technology, Inc. announced it is sampling the world's first vertically-integrated 176-layer NAND solid-state drive (SSD) for the data center. [More>>](#)

Business News

Edwards invests in new Arizona facility to support North America semiconductor growth

Edwards, the supplier of vacuum and abatement services and solutions to the global semiconductor industry, has announced its investment in a new manufacturing facility in Chandler. [More>>](#)

Leaders in semiconductors, packaging, IP suppliers, foundries and cloud service providers join forces to standardize chiplet ecosystem

Advanced Semiconductor Engineering, Inc. (ASE), AMD, Arm, Google Cloud, Intel Corporation, Meta, Microsoft Corporation, Qualcomm Incorporated, Samsung, and Taiwan Semiconductor Manufacturing Company announced the formation of an industry consortium that will establish a die-to-die interconnect standard and foster an open chiplet ecosystem. [More>>](#)

Count of semiconductor fabs using 300mm wafers projected to exceed 200 by 2026

At the end of 2021, there were 153 semiconductor fabs processing 300mm wafers for the fabrication of ICs, including CMOS image sensors, and non-IC products such as power discretes. [More>>](#)



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